Special Issue

Microelectromechanical Systems (MEMSs): Design, Fabrication, Integration, and Applications

Message from the Guest Editors

MEMSs play a pivotal role in enabling miniaturized high-performance sensors and actuators, and are instrumental in driving forward the ongoing intelligence revolution, where interconnected and intelligent systems and IoT applications rely on MEMS devices for data acquisition, processing, and control. Recent developments in the design methodology, fabrication, and integration techniques advance MEMSs toward intelligent microsystems. This Special Issue will be focused on the design, fabrication, and integration technology for enabling novel MEMS devices and applications in various electronic systems. In this Special Issue, original research articles and reviews are welcome. Research areas may include (but are not limited to) the following:

- The system-level modelling of MEMSs;
- The multiphysics simulation of MEMSs;
- Advanced materials in MEMSs;
- Novel fabrication and integration techniques for MEMSs:
- The design and implementation of electronic circuits for MEMSs;
- Artificial intelligence and MEMSs;
- Novel applications of MEMSs.

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Deadline for manuscript submissions

closed (15 May 2024)



Electronics

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About the Journal

Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guest-edited by leading experts in selected topics of interest.

Editor-in-Chief

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manuscripts are peer-reviewed and a first decision is provided to authors approximately 16.8 days after submission; acceptance to publication is undertaken in 2.4 days (median values for papers published in this journal in the first half of 2025).

